

Title (en)

Process for selective deposition of a metal layer

Title (de)

Verfahren zur selektiven Abscheidung einer Metallschicht

Title (fr)

Procédé de dépôt sélectif d' une couche métallique

Publication

EP 0926262 B1 20030326 (DE)

Application

EP 98121020 A 19981105

Priority

DE 19748888 A 19971105

Abstract (en)

[origin: DE19851101A1] Site selective coupling of multi-atom polar compound (I) to surface of a polymer substrate where regions of the surface are treated with electromagnetic radiation. Components in the base material of the polymer are converted to reactive centers and brought into contact with a liquid solution of the polar compound (I) to couple (I) to the reactive centers. An Independent claim is included for a process for the selective deposition of a metal layer onto the surface of a polymer substrate comprising: (A) irradiating the areas of the surface to be coated with electromagnetic radiation to produce reactive centers; (B) fixing the reactive functional groups on the surface with a noble metal compound by contact with a solution of one or more noble metal compounds (II); (C) depositing the metal layer in an electroless plating bath.

IPC 1-7

C23C 18/16

IPC 8 full level

C23C 18/16 (2006.01)

CPC (source: EP)

C23C 18/1605 (2013.01); **C23C 18/1608** (2013.01); **C23C 18/1612** (2013.01); **C23C 18/30** (2013.01)

Cited by

EP2581469A1; WO2013055786A1; US9538665B2

Designated contracting state (EPC)

DE FR

DOCDB simple family (publication)

DE 19851101 A1 19990506; DE 59807643 D1 20030430; EP 0926262 A1 19990630; EP 0926262 B1 20030326

DOCDB simple family (application)

DE 19851101 A 19981105; DE 59807643 T 19981105; EP 98121020 A 19981105